



Soitec appoints Senior Executive Vice President Strategic Alliances and names new Chief Financial Officer.

BERNIN, France, 30th September 2009 — Soitec (Euronext Paris), the world's leading supplier of engineered substrates for microelectronics, today announced that Iain Murray, currently Chief Financial Officer, has been appointed to the newly created position of Senior Executive Vice President Strategic Alliances, reporting to the Company's President, Andre-Jacques Auberton-Hervé. Following the recent successful fund raising, Murray's role will be to oversee and bring to fruition the Company's plans to invest in strategic partnerships to develop value-added innovative engineered substrates, using diverse high performance materials that enable pioneering low energy applications across a wide range of new markets beyond the traditional microprocessor domain.

Olivier Brice, who was named Deputy Finance Director in April this year will take over, with immediate effect, the position of Chief Financial Officer also reporting to the Company's President, Andre-Jacques Auberton-Hervé. Brice will focus on management of all financial initiatives to optimize performance of the Group and will continue to develop strong investor relations.

Brice (50) joined Soitec in 2005 initially to take responsibility for investor relations and financial communications and subsequently management of the group treasury function. He holds a BA in management and graduated from Sciences Po Paris, before starting his professional career as a banker. Brice then joined the Carbone Lorraine group, starting in investor relations before seeing his responsibilities extended to treasury and finance. Between 2001 and 2005, he was a manager of Gavin Anderson & Co., a financial communication firm.

Murray (58) who holds a law degree from Cambridge University and is a Fellow of the Institute of Chartered Accountants in England and Wales joined Soitec in 1996 as Chief Financial Officer and has played an integral role in the Company's development, including the original wide ranging agreement with SEH, the Company's initial public offering and all subsequent financial transactions on the Paris Stock Exchange.

About Soitec:

Soitec is the world's leading supplier of engineered substrates for advanced microelectronics. The Group produces a wide range of advanced materials, especially silicon-on-insulator (SOI) wafers based on its Smart Cut™ technology—the first high-volume application for this proprietary technology. SOI is currently seen as the platform of the future, paving the way to higher-performance, faster, and more economical chips.

Soitec currently produces over 80% of SOI wafers. Headquartered at Bernin in France, with two high-volume production units on site, Soitec also has offices in the US, Japan, and Taiwan, and a new production site is in the process of customers qualification in Singapore.

The Group has two other divisions: Picogiga International at Les Ulis in Paris and Tracit Technologies in Bernin. Picogiga is specialized in the development and manufacture of engineered substrates, from group III-V epitaxial semiconductor wafers and gallium nitride (GaN) wafers to composite substrates for the manufacture of high-frequency electronics and optoelectronic devices. Tracit is specialized in thin-film layer transfer technologies, used to manufacture engineered substrates for power ICs and microsystems, as well as generic circuit transfer technology for applications such as image sensors and 3D integration. Shares for the Soitec Group are listed on Euronext Paris. More information is available at www.soitec.com

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